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BGA TWTK-BGAP-10 plating kit

Product ID: 1872

Price: **9.00 EUR**

Product weight: **0.01 kg**

Description:

BGA TWTK-BGAP-10 plating kit it's a 11 set matrix for that's needed tool when you have to exchange BGA parts of your phone. It's supports Samsung S308 CPU, N188/N288 CPU, V200 CPU, E800 CPU, X600 Power IC, S300 UEM, E700 Power IC, E708 Flash, E630 CPU and E700 CPU chipsets. Click to link for bigger photo - [LINK](#)

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